

# Electroless Silver SLOTOCHEM AG 10

Electroless Silver SLOTOCHEM AG 10 is an acidic process for the deposition of silver on copper surfaces by charge exchange. It is suitable for plating of printed circuit boards in order to produce a surface that can be soldered. Therefore it's a lead-free alternative to the so far commonly used Hot-Air-Levelling with eutectic tin-lead solder.

Solderability of the deposited silver layers is excellent even after heat ageing of 4 h/155 °C. Since silver layers tend after longer storage at room temperature to formation of a silver-tarnish layer, therefore it's recommended to post-dip the parts in Antitarnish ALS 10 (BATH 06004-E) in order to maintain the excellent solderability.

Electroless deposited silver layers are ideal in combination with the lead-free solder alloys which are being currently implemented and which have silver content as well. However, they are also compatible with the traditional tin-lead based solders.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

#### Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at [www.schloetter.com/downloads](http://www.schloetter.com/downloads).

For the storage of chemical products the TRGS 510 must be followed.

**If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.**

